

12. The method of Claim 11 wherein mounting the land grid array socket to the power converter provides an electrical connection between the land grid array socket and the power converter.
13. The method of Claim 11 further comprising mounting the land grid array socket to an integrated circuit device affixed to a land grid array package.
14. The method of Claim 11 wherein mounting the land grid array socket to the power converter further comprises mounting the land grid array socket to a printed circuit board by vertically compressing an array of contacts on the land grid array socket with an array of corresponding contacts on the printed circuit board.
15. The method of Claim 14 wherein mounting the land grid array socket to the printed circuit board provides an electrical connection between the land grid array socket and the printed circuit board.
16. The method of Claim 11 wherein mounting the land grid array socket to the printed circuit board further comprises mounting the land grid array socket to a retention mechanism, the array of contacts on the land grid array socket mounted to the array of contacts on the printed circuit board through a relief in the retention mechanism.
17. The method of Claim 11 further comprising using the land grid array socket as a retention mechanism to hold the land grid array socket in proper alignment with the printed circuit board and in proper alignment with the power converter.

18. The method of Claim 11 wherein the power converter is adapted to convert voltage received from a power supply to a lower voltage and transmits the lower voltage to the land grid array socket.

If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 4/12, 2001



Michael A. Bernadicou  
Reg. No. 35,934

12400 Wilshire Blvd.  
Seventh Floor  
Los Angeles, CA 90025-1026  
(408) 720-8300